

## 300mA High PSRR, Low Noise LDO

### Regulator

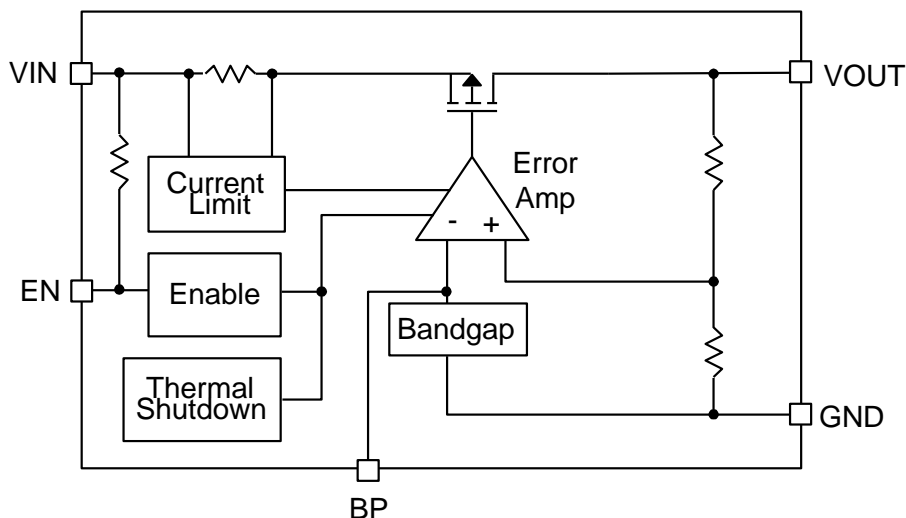
#### ❖ GENERAL DESCRIPTION

The AX6608 is a low dropout, high PSRR, low noise linear regulator with very low quiescent. It can supply 300mA output current with low dropout about 250mV. The Device includes pass element, error amplifier, band-gap, current-limit and thermal shutdown circuitry. The characteristics of low dropout voltage and less quiescent current make it good for some critical current application, for example, some battery powered devices. The typical quiescent current is approximately 30 $\mu$ A. In the shutdown mode, the maximum supply current is less than 1 $\mu$ A. Due to internal flexible design, result in extensively fixed output voltage versions is 1.0V to 3.3V per 0.1V steps. Built-in current-limit and thermal-shutdown functions prevent any fault condition from IC damage.

#### ❖ FEATURES

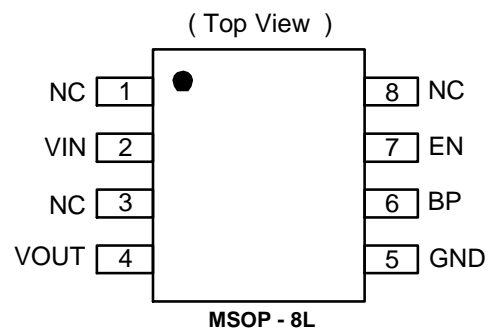
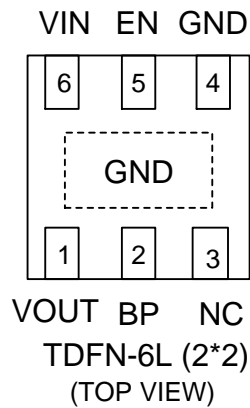
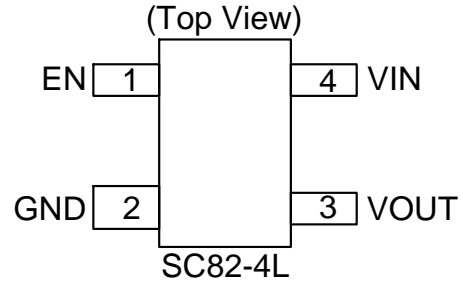
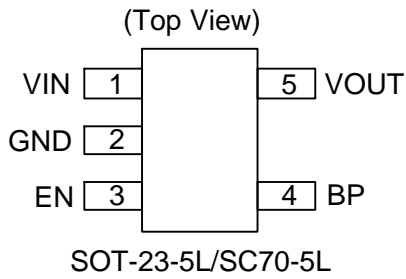
- Input voltage range : 2.8V~5.5V
- Dropout voltage is 250mV at 300mA output current
- Guaranteed 300mA output current
- Low quiescent current is 30 $\mu$ A (typ.)
- Maximum supply current in shutdown mode <1 $\mu$ A
- Fixed Output voltage is 1.0V to 3.3V by 0.1V steps.
- High PSRR=73dB@1KHz
- Fast transient response
- Current limit and thermal shutdown protection
- Available in the 5-Pin Pb-Free SOT-23, SC70, TDFN-6L, SC82-4L and MSOP-8L Packages

#### ❖ BLOCK DIAGRAM



❖ **PIN ASSIGNMENT**

The packages of AX6608 are SOT-23-5L, SC70-5L, SC82-4L, TDFN-6L and MSOP-8L; the pin assignment is given by:



Name	Description
<b>VIN</b>	Voltage input. The input capacitor in the range of 1uF to 10uF is sufficient.
<b>GND</b>	Ground
<b>EN</b>	Enable pin (Active High)
<b>BP</b>	Reference Noise Bypass (The Bypass capacitor $\geq 1nF$ )
<b>VOUT</b>	Output Voltage, The AX6608 is stable with an output capacitor 1uF for greater.
<b>NC</b>	No Connect

❖ ORDER/MARKING INFORMATION

Order Information	
<p style="text-align: center;"><b>AX6608-XX XX X</b></p> <div style="display: flex; justify-content: space-around;"> <div style="text-align: left;"> <p>Output voltage</p> <p>10 : 1.0V 11 : 1.1V ..... 33 : 3.3V</p> </div> <div style="text-align: left;"> <p>Package</p> <p>A5 : SC70-5L B : SOT-23-5L Z6 : TDFN-6L (2*2) SC : SC82-4L U8 : MSOP-8L</p> </div> <div style="text-align: left;"> <p>Packing</p> <p>Blank: Bag A : Taping</p> </div> </div>	
Top Marking (TDFN-6L)	Top Marking (MSOP-8L)
<p><b>LL</b> → Output type Refer Identification Code</p> <p><b>YWX</b> → ID Code: Internal</p> <p>Week: 01~26(A~Z) 27~52(a~z)</p> <p>Year : 1 = 2011 2 = 2012</p>	<p>Logo ← <b>AX</b> 6 6 0 8 → Part number</p> <p><b>YYWWX</b> → ID code:internal</p> <p>Week: 01~52 Year: 11=2011 12=2012</p>
Top Marking (SC70-5L/SC82-4L)	Top Marking (SOT-23-5L)
<p><b>LLYW</b> → WW : 01~26(A~Z) 27~52(a~z)</p> <p><b>LLYW</b> → ID Code: internal</p> <p>Year : 1 = 2011 2 = 2012</p> <p>Identification code</p>	<p><b>LLYWX</b> → ID code: internal</p> <p>Week: 01~26(A~Z) 27~52(a~z)</p> <p>Year: 1= 2011 2= 2012</p> <p>Identification code</p>

Appendix

Part Number	Identification Code		Part Number	Identification Code	
	SOT-23-5L/SC70-5L	SC82-4L/TDFN-6L		SOT-23-5L/SC70-5L	SC82-4L/TDFN-6L
AX6608-1.0V	U0		AX6608-2.2V	UO	
AX6608-1.1V	UA		AX6608-2.3V	Uv	
AX6608-1.2V	UB		AX6608-2.4V	UT	
AX6608-1.3V	U3		AX6608-2.5V	UF	
AX6608-1.4V	U4		AX6608-2.6V	Uf	
AX6608-1.5V	UC		AX6608-2.7V	Uw	
AX6608-1.6V	US		AX6608-2.8V	UG	
AX6608-1.7V	UX		AX6608-2.9V	Uh	
AX6608-1.8V	UD		AX6608-3.0V	UH	
AX6608-1.9V	Ua		AX6608-3.1V	Ux	
AX6608-2.0V	Ue		AX6608-3.2V	UU	
AX6608-2.1V	Ub		AX6608-3.3V	UI	

❖ **ABSOLUTE MAXIMUM RATINGS** (at  $T_A=25^{\circ}\text{C}$ )

Characteristics		Symbol	Rating	Unit
V <sub>IN</sub> Pin Voltage		V <sub>IN</sub>	GND - 0.3 to GND + 6	V
Output Voltage		V <sub>OUT</sub>	GND - 0.3 to V <sub>IN</sub> + 0.3	V
Enable Voltage		V <sub>EN</sub>	GND - 0.3 to GND + 6	V
Power Dissipation		PD	Internally limited	mW
Storage Temperature Range		T <sub>ST</sub>	-40 to +150	°C
Operating Temperature Range		T <sub>OP</sub>	-40 to +85	°C
Junction Temperature		T <sub>J</sub>	-40 to +125	°C
Thermal Resistance from Junction to case	SOT-23-5L	θ <sub>JC</sub>	180	°C/W
	SC70-5L		230	
	TDFN-6L		25	
	SC82-4L		120	
	MSOP-8L		45	
Thermal Resistance from Junction to ambient	SOT-23-5L	θ <sub>JA</sub>	250	°C/W
	SC70-5L		280	
	TDFN-6L		120	
	SC82-4L		400	
	MSOP-8L		200	

Note: θ<sub>JA</sub> is measured with the PCB copper area of approximately 1 in<sup>2</sup> (Multi-layer). That need connect to GND (EP) pin.

### ❖ ELECTRICAL CHARACTERISTICS

( $V_{IN}=V_{OUT}+1V$  or  $V_{IN}=2.8V$  whichever is greater,  $C_{IN}=C_{OUT}=1\mu F$ ,  $T_A=25^{\circ}C$ , unless otherwise noted)

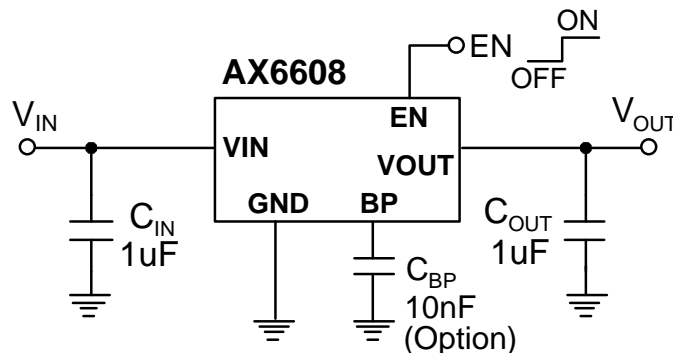
Characteristics	Symbol	Conditions	Min	Typ	Max	Units	
Input Voltage	$V_{IN}$	(Note1)	2.8	-	5.5	V	
Output Voltage Accuracy	$\Delta V_{OUT}$	$I_{OUT}=1mA$	-2	-	+2	%	
Quiescent Current	$I_Q$	$I_{OUT}=0mA$	-	30	60	$\mu A$	
Dropout Voltage (Note2)	$V_{DROP}$	$I_{OUT}=300mA$	$1.0V \leq V_{OUT} \leq 2.0V$	-	1500	-	mV
			$1.5V < V_{OUT} \leq 2.0V$	-	1000	-	
			$2.0V < V_{OUT} \leq 2.8V$	-	350	-	
			$2.8V < V_{OUT} \leq 3.3V$	-	250	-	
Current Limit	$I_{LIMIT}$	$R_{LOAD}=1\Omega$	300	-	-	mA	
Line Regulation	$\Delta V_{LINE}$	$I_{OUT}=1mA$ , $V_{IN}=V_{OUT}+1V$ to 5V	-	1	5	mV	
Load Regulation (Note3)	$\Delta V_{LOAD}$	$I_{OUT}=0m\sim 150mA$	-	6	20	mV	
Ripple Rejection	PSRR	$C_{OUT}=1\mu F$ , $I_{OUT}=1mA$	$F=1KHz$	-	-73	-	dB
			$F=10K$	-	-60	-	
Enable Input Threshold	$V_{ENH}$		1.4	-	-	V	
	$V_{ENL}$		-	-	0.4		
Enable Pin Current	$I_{EH}$	$V_{EN}=V_{IN}$	-	-	0.1	$\mu A$	
Shutdown Current	$I_{SD}$	$V_{IN}=3.6V$ , $V_{EN}=0V$	-	-	1	$\mu A$	
Temperature Coefficient	$T_C$	$I_{OUT}=1mA$ , $V_{IN}=5V$	-	50	-	ppm/ $^{\circ}C$	
Temperature Shutdown	$T_S$		-	160	-	$^{\circ}C$	
Temperature Shutdown Hysteresis	$T_{SH}$		-	25	-	$^{\circ}C$	

Note1. Minimum  $V_{IN}$  voltage is defined by output adds a dropout voltage.

Note2. The dropout voltage is defined as  $V_{IN}-V_{OUT}$ , which is measured when  $V_{OUT}$  drop about 100mV.

Note3. Regulation is measured at constant junction temperature by using pulsed testing with a low ON time.

## ❖ APPLICATION CIRCUIT



## ❖ FUNCTION DESCRIPTIONS

A minimum of 1uF capacitor must be connected from  $V_{OUT}$  to ground to insure stability. Typically a large storage capacitor is connected from  $V_{IN}$  to ground to ensure that the input voltage does not sag below the minimum dropout voltage during the load transient response. This pin must always be dropout voltage higher than  $V_{OUT}$  in order for the device to regulate properly.

## ❖ APPLICATION INFORMATION

Like any low-dropout regulator, the AX6608 requires input and output decoupling capacitors. The device is specifically designed for portable applications requiring minimum board space and smallest components. These capacitors must be correctly selected for good performance. Please note that linear regulators with a low dropout voltage have high internal loop gains which require care in guarding against oscillation caused by insufficient decoupling capacitance.

### Capacitor Selection

Normally, use a 1μF capacitor on the input and a 1μF capacitor on the output of the AX6608. Larger input capacitor values and lower ESR provide better supply-noise rejection and transient response. A large value output capacitor may be necessary if large, fast transients are anticipated and the device is located several inches from the power source. The capacitors is recommended to use 1uF X5R or X7R dielectric ceramic capacitors with 30mΩ to 50mΩ ESR range between device outputs to ground for transient stability.

## Input-Output (Dropout) Voltage

A regulator's minimum input-to-output voltage differential (dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the device uses a PMOS, its dropout voltage is a function of drain-to source on-resistance,  $R_{DS(ON)}$ , multiplied by the load current:

$$V_{DROPOUT} = V_{IN} - V_{OUT} = R_{DS(ON)} \times I_{OUT}$$

## Current Limit and Thermal Shutdown Protection

In order to prevent overloading or thermal condition from damaging the device, AX6608 regulator has internal thermal and current limiting functions designed to protect the device. It will rapidly shut off PMOS pass element during overloading or over temperature condition.

## Thermal Considerations

The AX6608 series can deliver a current of up to 300mA over the full operating junction temperature range. However, the maximum output current must be dated at higher ambient temperature to ensure the junction temperature does not exceed 125°C. With all possible conditions, the junction temperature must be within the range specified under operating conditions. Power dissipation can be calculated based on the output current and the voltage drop across regulator.

$$PD = (V_{IN} - V_{OUT}) I_{OUT}$$

The final operating junction temperature for any set of conditions can be estimated by the following thermal equation:

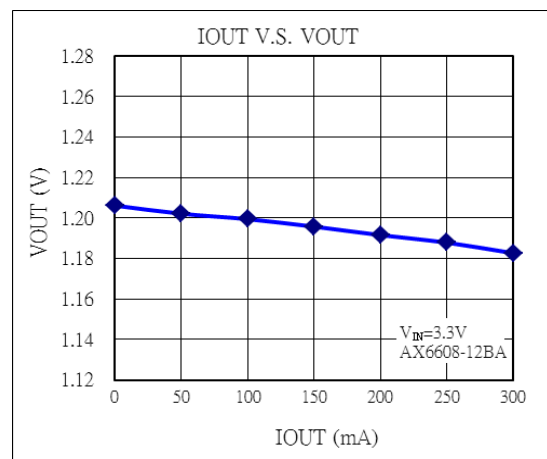
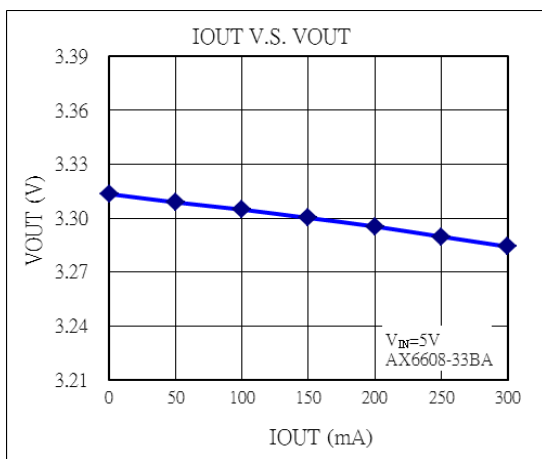
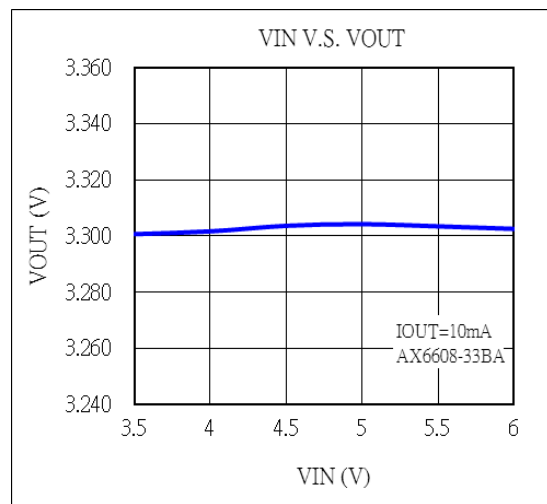
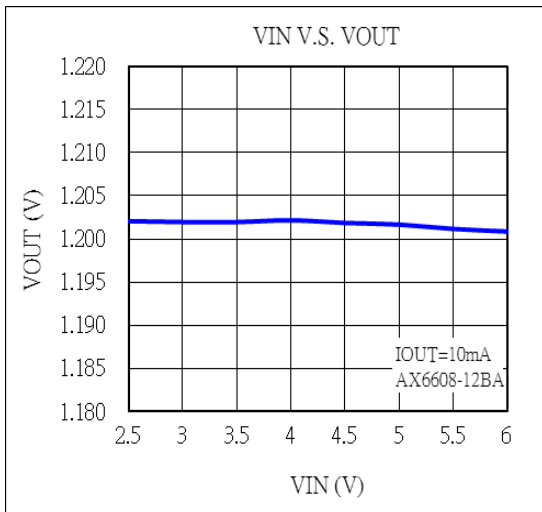
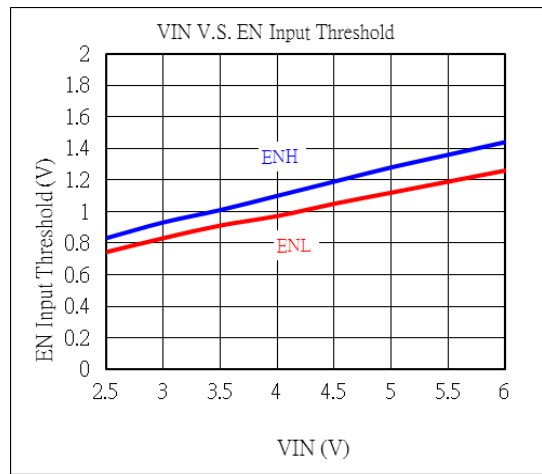
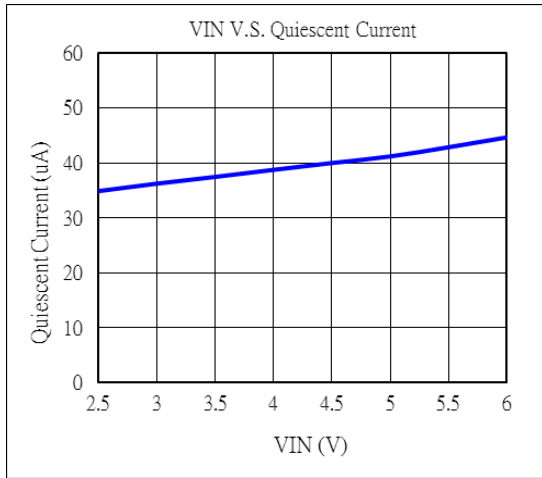
$$PD (MAX) = (T_{J(MAX)} - T_A) / \theta_{JA}$$

Where  $T_{J(MAX)}$  is the maximum junction temperature of the die (125°C) and  $T_A$  is the maximum ambient temperature. The junction to ambient thermal resistance ( $\theta_{JA}$ ) for SOT-23-5L package at recommended minimum footprint is 250°C/W.

## PCB Layout

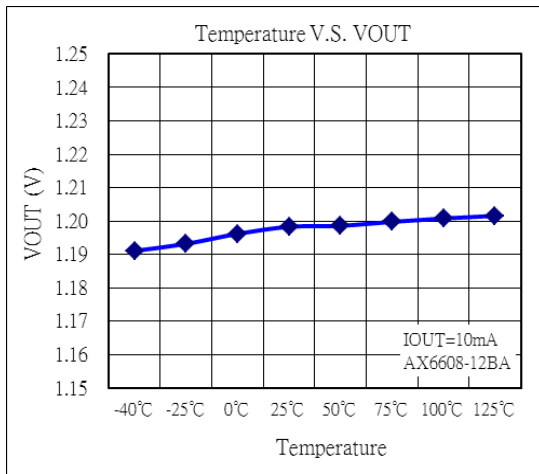
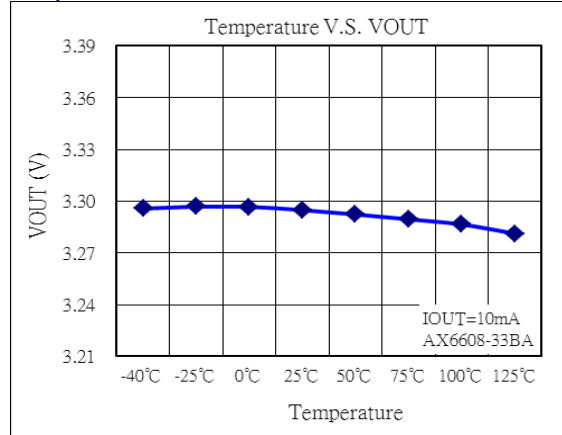
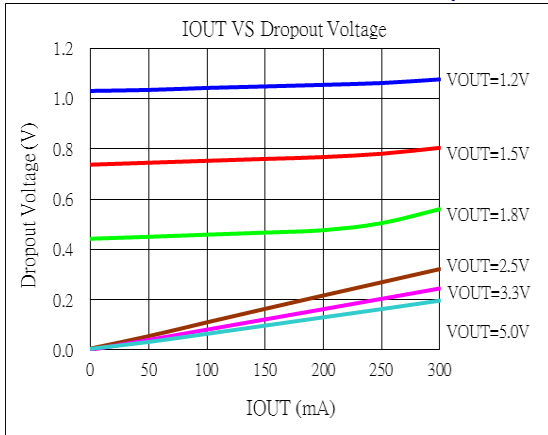
An input capacitance of  $\cong 1\mu F$  is required between the AX6608 input pin and ground (the amount of the capacitance may be increased without limit), this capacitor must be located a distance of not more than 1cm from the input and return to a clean analog ground. Input capacitor can filter out the input voltage spike caused by the surge current due to the inductive effect of the package pin and the printed circuit board's routing wire. Otherwise, the actual voltage at the VIN pin may exceed the absolute maximum rating. The output capacitor also must be located a distance of not more than 1cm from output to a clean analog ground. Because it can filter out the output spike caused by the surge current due to the inductive effect of the package pin and the printed circuit board's routing wire.

❖ TYPICAL CHARACTERISTICS



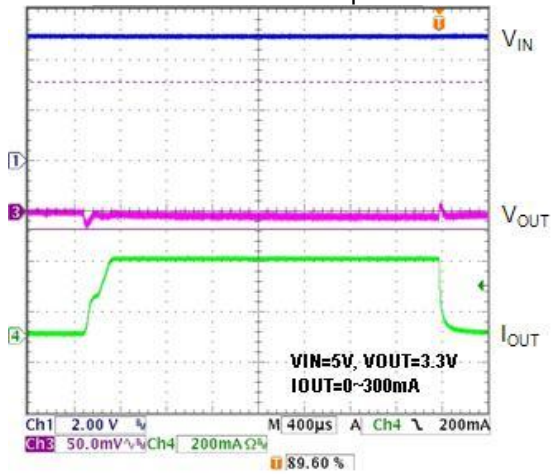


❖ TYPICAL CHARACTERISTICS (CONTINUES)

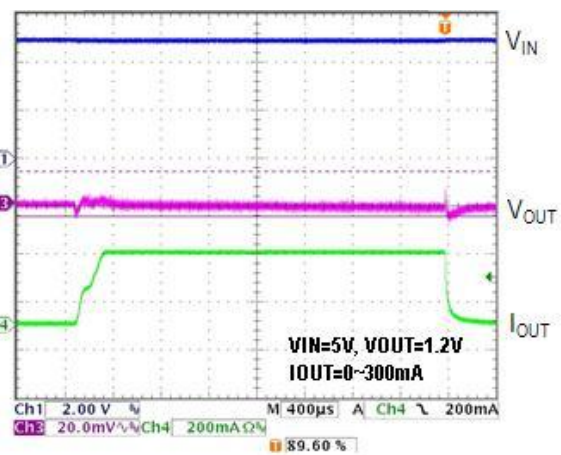


❖ TYPICAL CHARACTERISTICS (CONTINUES)

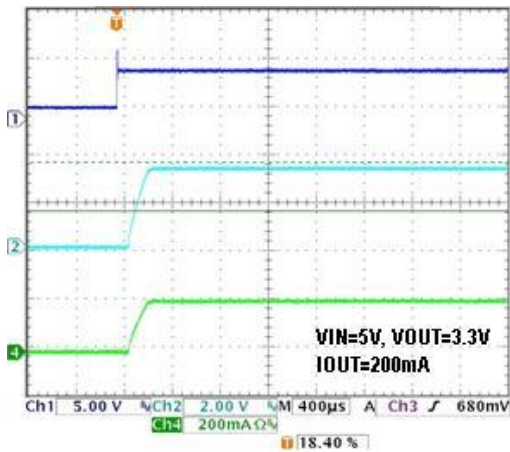
Load transient response



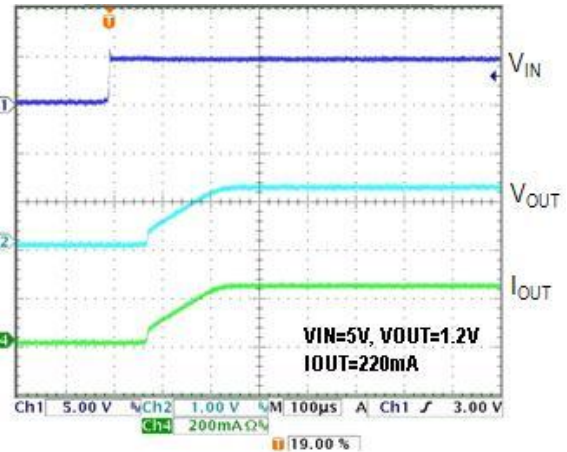
Load transient response



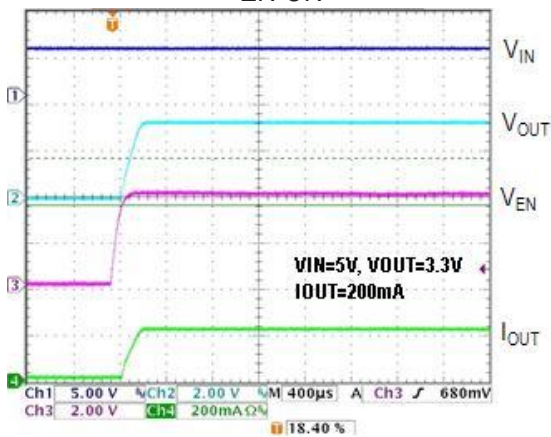
Power ON



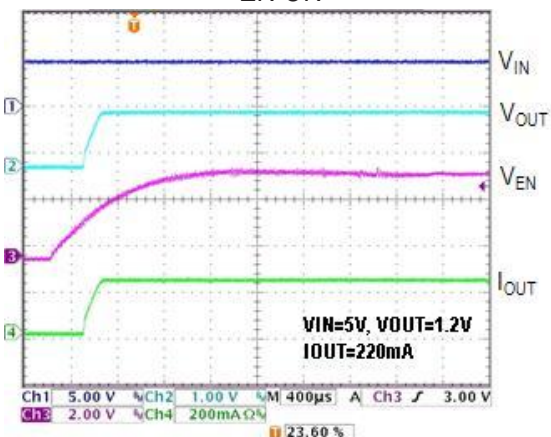
Power ON



EN ON

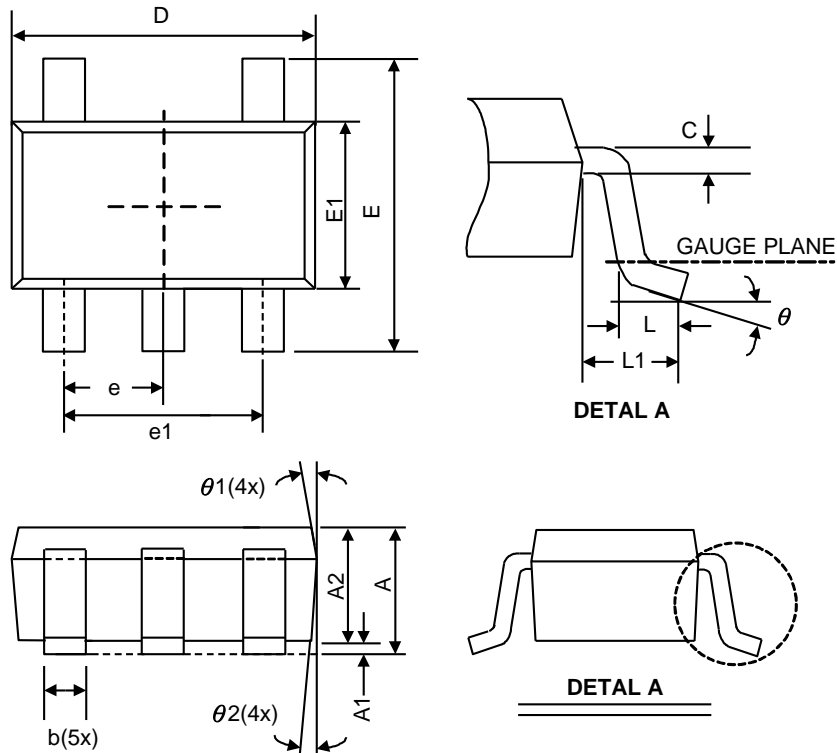


EN ON



❖ PACKAGE OUTLINES

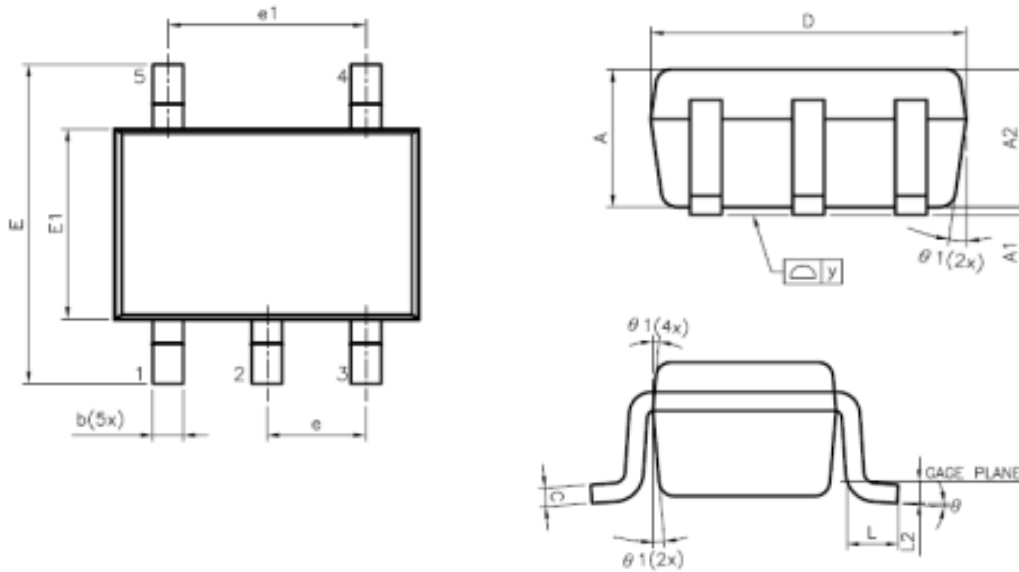
(1) SOT-23-5L



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.45	-	-	0.057
A1	0.00	0.08	0.15	0	0.003	0.006
A2	0.90	1.10	1.30	0.035	0.043	0.051
b	0.30	0.40	0.50	0.012	0.016	0.020
C	0.08	0.15	0.22	0.003	0.006	0.009
D	2.70	2.90	3.10	0.106	0.114	0.122
E1	1.40	1.60	1.80	0.055	0.063	0.071
E	2.60	2.80	3.00	0.102	0.110	0.118
L	0.30	0.45	0.60	0.012	0.018	0.024
L1	0.50	0.60	0.70	0.020	0.024	0.028
e1	1.9 BSC			0.075 BSC		
e	0.95 BSC			0.037 BSC		
$\theta$	0°	4°	8°	0°	4°	8°
$\theta 1$	5°	10°	15°	5°	10°	15°
$\theta 2$	5°	10°	15°	5°	10°	15°

JEDEC outline: MO-178 AA

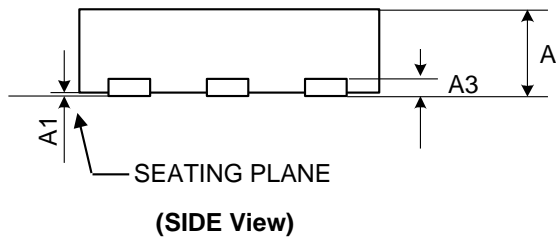
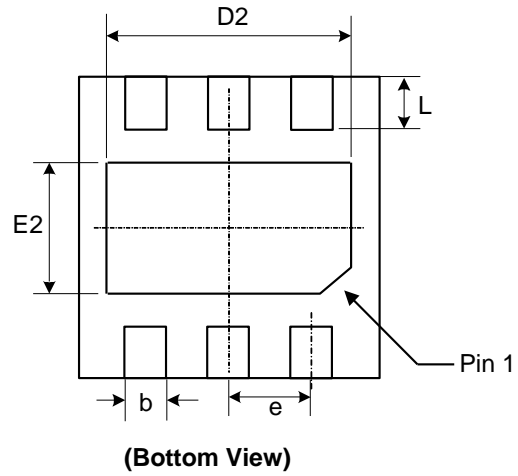
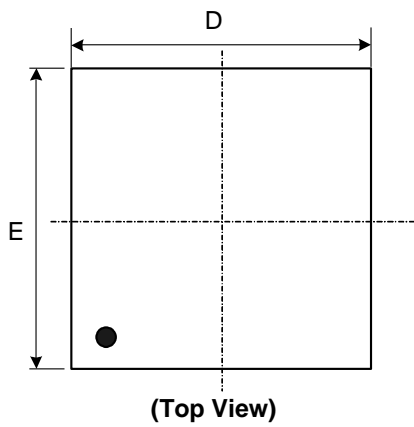
(2) SC70-5L



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70	0.90	1.00	0.028	0.035	0.039
b	0.20	0.30	0.40	0.008	0.012	0.016
C	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.071	0.079	0.087
E	1.95	2.20	2.45	0.077	0.087	0.096
E1	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65 BSC			0.026 BSC		
e1	1.30 BSC			0.051 BSC		
L	0.26	0.36	0.46	0.01	0.014	0.018
L2	0.15 BSC			0.006 BSC		
y	-	-	0.10	-	-	0.004
theta	0°	4°	8°	0°	4°	8°
theta 1	4°	-	12°	4°	-	12°

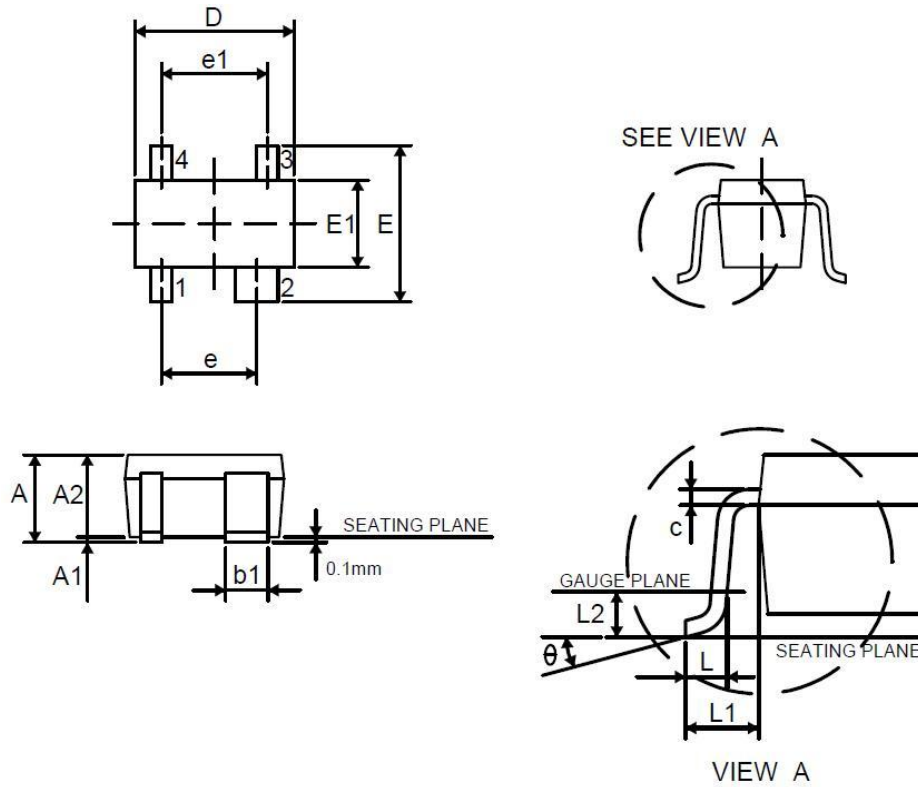
Mold flash shall not exceed 0.15mm per side

(3) TDFN-6L



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.70	0.75	0.80	0.028	0.030	0.031
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.203 REF.			0.008 REF.		
b	0.20	0.28	0.35	0.009	0.011	0.013
D	1.95	2.00	2.05	0.077	0.079	0.081
D2	1.35	1.50	1.65	0.055	0.059	0.063
E	1.95	2.00	2.05	0.077	0.079	0.081
E2	0.75	0.90	1.05	0.031	0.035	0.039
e	0.65 BSC.			0.026 BSC.		
L	0.20	0.30	0.40	0.008	0.012	0.016

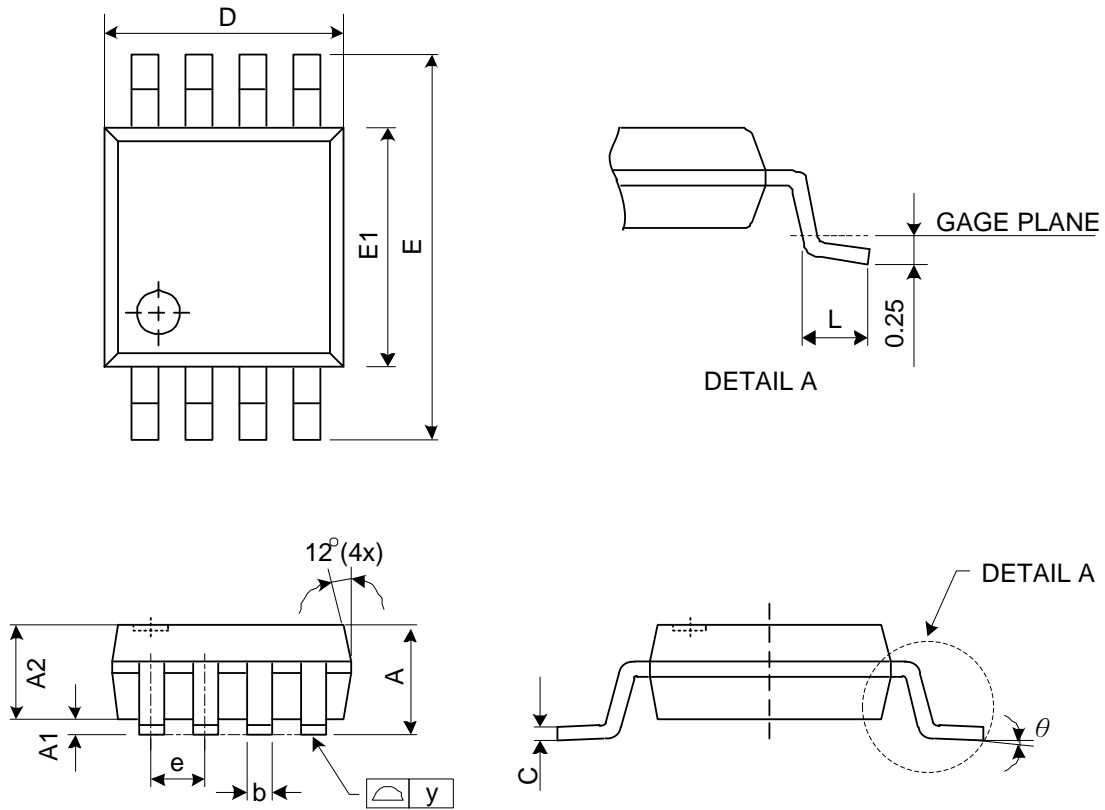
(4) SC82-4L



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.10	-	-	0.043
A1	0.00	-	0.10	0.000	-	0.004
A2	0.70	0.90	1.00	0.028	0.035	0.039
b	0.15	-	0.30	0.006	-	0.012
b1	0.30	-	0.60	0.012	-	0.024
C	0.08	-	0.22	0.003	-	0.009
D	2.00 BSC			0.078BSC		
E	2.10 BSC			0.083 BSC		
E1	1.25 BSC			0.049 BSC		
e	1.30 BSC			0.051 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
θ	0°	-	8°	0°	-	8°

MOLD FLASH, INTERLEAD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.2mm PER SIDE.

(5) MSOP-8L



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	-	-	1.1	-	-	0.043
A1	0	0.08	0.15	0	0.003	0.006
A2	0.75	0.85	0.95	0.03	0.033	0.037
b	0.22	0.3	0.38	0.009	0.012	0.015
C	0.08	0.15	0.23	0.003	0.006	0.009
D	2.9	3	3.1	0.114	0.118	0.122
E	4.8	4.9	5	0.189	0.193	0.197
E1	2.9	3	3.1	0.114	0.118	0.122
e	0.65 BSC			0.026 BSC		
L	0.4	0.6	0.8	0.016	0.024	0.031
y	-	-	0.1	-	-	0.004
$\theta$	0°	4°	8°	0°	4°	8°

JEDEC outline: MO-187 AA